# PHOTON IS OUR BUSINESS



# Photodiode arrays with amplifiers

S13885/S13886 series

# Photodiode arrays combined with signal processing IC for X-ray detection

The S13885/S13886 series are photodiode arrays with amplifiers having a phosphor sheet attached to the photosensitive area for X-ray detection. Improvement in the signal processing IC chip has achieved higher sensitivity compared to the previous products (S11865/S11866 series). The signal processing IC chip is formed by CMOS process and incorporates a timing generator, shift register, charge amplifier array, clamp circuit and hold circuit, making the external circuit configuration simple. A long and narrow image sensor can be configured by arranging multiple arrays in a row.

#### Features

- Data rate: 1 MHz max.
- **■** Element pitch: 3 types available S13885-128G: 0.4 mm pitch × 128 ch S13885-256G: 0.2 mm pitch × 256 ch S13886-128G: 0.8 mm pitch × 128 ch
- 3.3 V power supply operation
- ➡ Simultaneous integration method by using a charge amplifier array
- Low dark current due to zero-bias photodiode operation
- Integrated clamp circuit allows low noise and wide dynamic range.
- Integrated timing generator allows operation at two different pulse timings.
- Detectable energy range: 30 k to 100 keV

# Applications

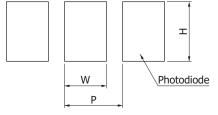
- Line sensors for X-ray detection
- Long and narrow line sensors

#### **Structure**

Parameter	Symbol*1	S13885-128G	S13885-256G	S13886-128G	Unit		
Element pitch	Р	0.4	0.2	0.8	mm		
Element width	W	0.3	0.1	0.7	mm		
Element height	Н	0.6	0.3	0.8	mm		
Number of elements	-	128	256	128	-		
Effective area length	-	51.2	51.2	102.4	mm		
Board material	-	Glass epoxy					

<sup>\*1:</sup> Refer to following figure.

# Enlarged drawing of photosensitive area



KMPDC0072F4

# ♣ Absolute maximum ratings (Ta=25 °C unless otherwise noted)

Parameter	Symbol	Value	Unit
Supply voltage	Vdd	-0.3 to +4.2	V
Reference voltage	Vref	-0.3 to +4.2	V
Photodiode voltage	Vpd	-0.3 to +4.2	V
Gain selection terminal voltage	Vgain	-0.3 to +4.2	V
Master/slave selection voltage	Vms	-0.3 to +4.2	V
Clock pulse voltage	V(CLK)	-0.3 to +4.2	V
Reset pulse voltage	V(RESET)	-0.3 to +4.2	V
External start pulse voltage	V(EXTSP)	-0.3 to +4.2	V
Operating temperature*2	Topr	-5 to +60	°C
Storage temperature*2	Tstg	-10 to +70	°C

<sup>\*2:</sup> No dew condensation

When there is a temperature difference between a product and the surrounding area in high humidity environment, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

# **=** Recommended terminal voltage (Ta=25 °C)

Parameter		Symbol	Min.	Тур.	Max.	Unit
Supply voltage		Vdd	3.0	3.3	3.6	V
Reference voltage		Vref	Vdd - 1.0	Vdd - 0.8	Vdd - 0.6	V
Photodiode voltage		Vpd	-	Vref	-	V
Gain selection terminal	High gain	Vanin	Vdd - 0.25	Vdd	Vdd + 0.25	V
voltage	Low gain	Vgain	0	-	0.25	V
Master/alaya salection valtage	High level*3	Vms	Vdd - 0.25	Vdd	Vdd + 0.25	V
Master/slave selection voltage	Low level*4		0	-	0.25	V
Clock pulse veltage	High level	V((CLK)	Vdd - 0.25	Vdd	Vdd + 0.25	V
Clock pulse voltage	Low level	V(CLK)	0	-	0.25	V
Poset pulse veltage	High level	\//DECET\	Vdd - 0.25	Vdd	Vdd + 0.25	V
Reset pulse voltage	Low level	V(RESET)	0	-	0.25	V
External start pulse veltage	High level	\/(EVTCD)	Vdd - 0.25	Vdd	Vdd + 0.25	V
External start pulse voltage	Low level	V(EXTSP)	0	-	0.25	V

<sup>\*3:</sup> Parallel

# **■** Electrical characteristics [Ta=25 °C, Vdd=3.3 V, V(CLK)=V(RESET)=3.3 V]

Pa	rameter	Symbol	Min.	Тур.	Max.	Unit	
Clock pulse frequency	*5	f(CLK)	40	-	4000	kHz	
Line rate*6	S13885/S13886-128G	LR	-	-	7568	lines/s	
Line rate	S13885-256G		-	-	3844	lines/s	
Output impedance		Zo	-	3	-	kΩ	
Current concumption	S13885/S13886-128G	To	-	36	-	A	
Current consumption	S13885-256G	Ic	-	72	-	mA	
Charge amplifier feedback High gain		Cf	-	0.125	-	nE	
capacitance	Low gain	CI	-	0.25	-	pF	

<sup>\*5:</sup> Video data rate is 1/4 of f(CLK).



<sup>\*4:</sup> Serial at 2nd or later stages

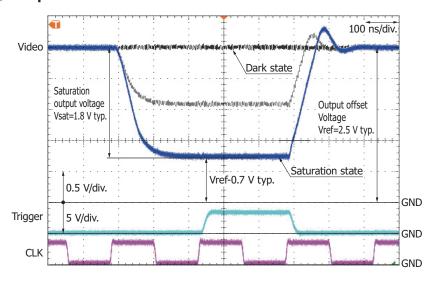
<sup>\*6:</sup> The values depend on the clock pulse frequency.

# Electrical and optical characteristics [Ta=25 °C, Vdd=3.3 V, V(CLK)=V(RESET)=3.3 V, Vgain=3.3 V (high gain), 0 V (low gain)]

Parameter		Cumbal	S13885-128G		S13885-256G		S13886-128G		Linit			
		Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
Peak sensitivity w	avelength*7	λр	-	720	-	-	720	-	-	720	-	nm
Dark output	High gain	VD	-	0.02	0.2	-	0.02	0.2	-	0.02	0.2	mV
voltage*8	3 3		-	0.01	0.1	-	0.01	0.1	-	0.01	0.1	IIIV
Saturation output	voltage	Vsat	Vref - 1.0	Vref - 0.7	-	Vref - 1.0	Vref - 0.7	-	Vref - 1.0	Vref - 0.7	-	V
Saturation	High gain		-	0.3	0.4	-	1.8	2.3	-	0.1	0.13	$mlx \cdot s$
exposure*7 *9	Low gain	Pin_sat	-	0.6	0.8	-	3.6	4.5	-	0.2	0.26	$  IIIIx \cdot S  $
Photosensitivity*7 *9	High gain	C	4800	6000	-	800	1000	-	14080	17600	-	\//\
Photosensitivity	Low gain	Sw	2400	3000	-	400	500	-	7040	8800	-	$V/lx \cdot s$
Photoresponse	3 channels from both ends	DDNIII	-	-	-55, +10	-	-	-70, +10	-	-	-35, +10	%
nonuniformity*10	All channels excluding 3 channels from both ends	PRNU	-	-	±10	-	-	±10	-	-	±10	70
Readout noise*11	High gain	Nread	-	1.0	1.5	-	0.6	0.9	-	1.7	2.6	mV rms
	Low gain	iviedu	-	0.6	0.9	-	0.4	0.6	-	1.0	1.5	IIIV IIIIS
Output offset volt	age*12	Voffset	-	Vref	-	-	Vref	-	-	Vref	-	V

<sup>\*7:</sup> Measured without phosphor sheet

### Output waveform of one element



<sup>\*8:</sup> Integration time ts=1 ms

<sup>\*9:</sup> Measured with a 2856 K tungsten lamp

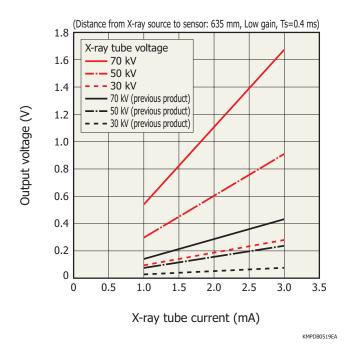
<sup>\*10:</sup> Photoresponse nonuniformity (PRNU) is the output nonuniformity that occurs when the photosensitive area is uniformly illuminated by X-ray (tube voltage: 70 kV) which is approx. 50% of the saturation level. PRNU is defined as follows: PRNU =  $\Delta X/X \times 100$  [%]

X: average output of all elements,  $\Delta X$ : difference between X and the maximum or minimum output, whichever is larger.

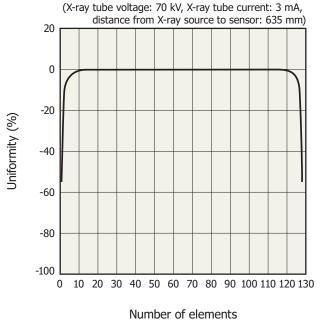
<sup>\*11:</sup> Video data rate=1 MHz, dark state, ts=1 ms

<sup>\*12:</sup> Video output is negative-going output with respect to the output offset voltage.

# X-ray output example (S13885-128G)

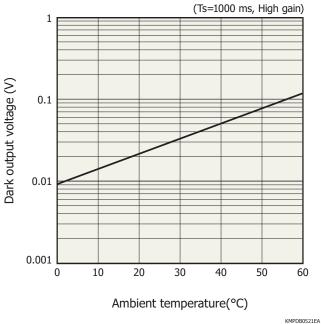


# Uniformity example of X-ray output (S13885-128G)



KMPDB0520EA

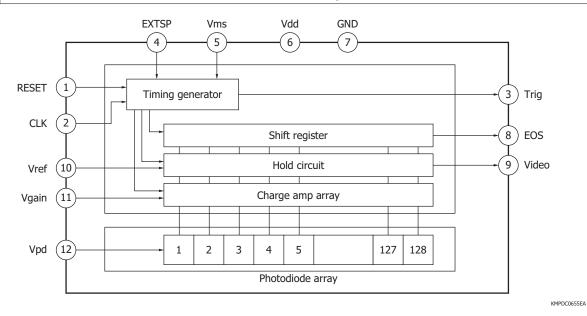
# Dark output voltage vs. ambient temperature (typical example)



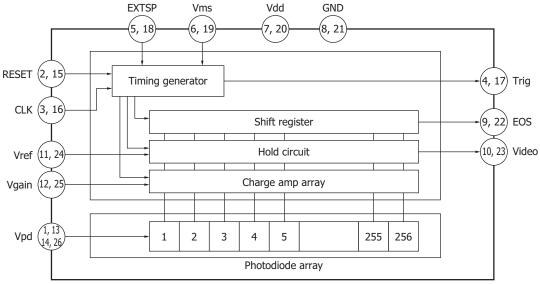
KI-II DD0321LA

# **Block diagram**

# S13885-128G, S13886-128G



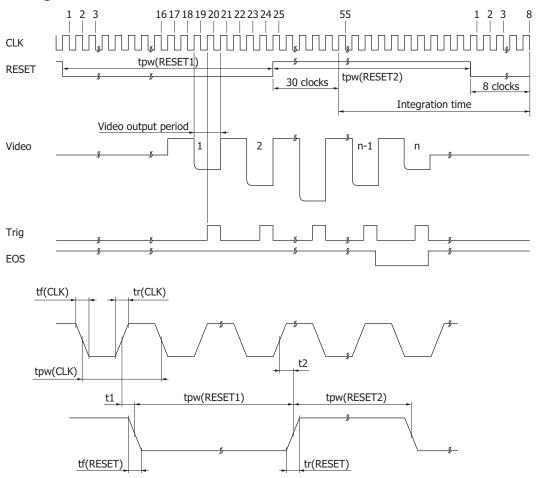
# S13885-256G



KMPDC0506EA

KMPDC0651EA

# - Timing chart



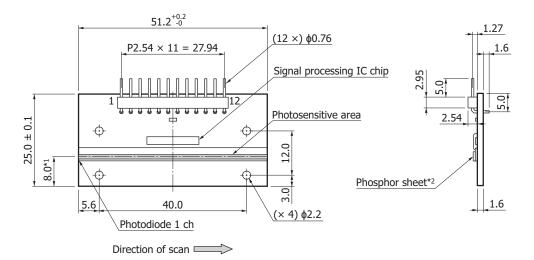
Parameter	Symbol	Min.	Typ.	Max.	Unit
Clock pulse width	tpw(CLK)	250	-	25000	ns
Clock pulse rise/fall times	tr(CLK), tf(CLK)	0	20	30	ns
Reset pulse width 1	tpw(RESET1)	25	-	-	CLK
Reset pulse width 2	tpw(RESET2)	40	-	-	CLK
Reset pulse rise/fall times	tr(RESET), tf(RESET)	0	20	30	ns
Clock pulse-reset pulse timing 1	t1	-20	0	20	ns
Clock pulse-reset pulse timing 2	t2	-20	0	20	ns

- 1. The internal timing circuit starts operation at the falling edge of CLK immediately after a RESET pulse goes low.
- 2. When the falling edge of this CLK is counted as 1 clock, the video signal of the 1st channel appears between 18.5 clocks and 20.5 clocks. Subsequent video signals appear every 4 clocks.
- 3. The trigger pulse for the 1st channel rises at a timing of 19.5 clocks and then rises every 4 clocks. The rising edge of each trigger pulse is the recommended timing for data acquisition.
- 4. Signal charge integration time equals [the high period of a RESET pulse 22 clocks]. The charge integration starts at the 30th clock after the rise of the RESET pulse and ends at the 8th clock after the fall of the RESET pulse. After the RESET pulse next changes from high to low, signals integrated within this period are sequentially read out as time-series signals by the shift register operation. The rise and fall of a RESET pulse must be synchronized with the rise of a CLK pulse, but the rise of a RESET pulse must be set outside the video output period. One cycle of RESET pulses cannot be set shorter than the time equal to [16.5 + 4 × N (number of elements)] clocks.
- 5. The video signal after an EOS signal output becomes a high impedance state, and the video output will be indefinite.



### Dimensional outlines (unit: mm)

#### S13885-128G



Tolerance unless otherwise noted: ±0.2

\*1: Distance from board bottom to photosensitive area center Board: G10 glass epoxy Connector: PRECI-DIP DURTAL 800-10-012-20-001101

\*2: Phosphor sheet specifications

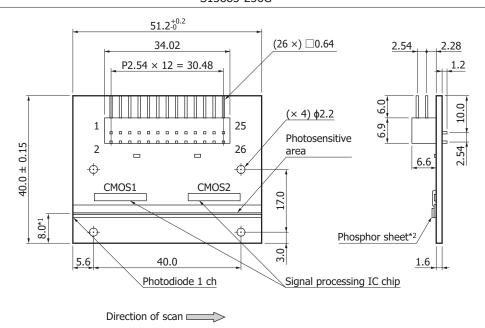
· Material: Gd<sub>2</sub>O<sub>2</sub>S: Tb

· Phosphor thickness: 300 µm typ.

· Detectable energy range: 30 k to 100 keV

KMPDA0576EA

# S13885-256G



Tolerance unless otherwise noted: ±0.2

\*1: Distance from board bottom to photosensitive area center Board: G10 glass epoxy

Connector: JAE (Japan Aviation Electronics Industry, Limited) PS-26PE-D4LT1-PN1

\*2: Phosphor sheet specifications

· Material: Gd<sub>2</sub>O<sub>2</sub>S: Tb

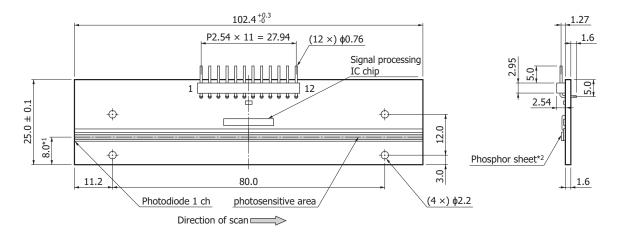
 $^{\circ}$  Phosphor thickness: 300  $\mu m$  typ.

· Detectable energy range: 30 k to 100 keV

KMPDA0577EA



### S13886-128G



Tolerance unless otherwise noted: ±0.2

- \*1: Distance from board bottom to photosensitive area center Board: G10 glass epoxy Connector: PRECI-DIP DURTAL 800-10-012-20-001101
- \*2: Photodiode array with phosphor sheet
  - · Material: Gd<sub>2</sub>O<sub>2</sub>S:Tb

  - Phosphor thickness: 300 μm typ.
    Detectable energy range: 30 k to 100 keV

KMPDA0578EA

### **₽** Pin connections

# S13885-128G, S13886-128G

Pin no.	Symbol	Name	Note
1	RESET	Reset pulse	Pulse input
2	CLK	Clock pulse	Pulse input
3	Trig	Trigger pulse	Positive-going pulse output
4	EXTSP	External start pulse	Pulse input
5	Vms	Master/slave selection voltage	Voltage input
6	Vdd	Supply voltage	Voltage input
7	GND	Ground	
8	EOS	End of scan	Negative-going pulse output
9	Video	Video output	Negative-going output from Vref
10	Vref	Reference voltage	Voltage input
11	Vgain	Gain selection terminal voltage	Voltage input
12	Vpd	Photodiode voltage	Voltage input

# S13885-256G

Pin no.	CMOS1	Pin no.	CMOS2	Name	Note
1	Vpd	14	Vpd	Photodiode voltage	Voltage input
2	RESET	15	RESET	Reset pulse	Pulse input
3	CLK	16	CLK	Clock pulse	Pulse input
4	Trig	17	Trig	Trigger pulse	Positive-going pulse output
5	EXTSP	18	EXTSP	External start pulse	Pulse input
6	Vms	19	Vms	Master/slave selection voltage	Voltage input
7	Vdd	20	Vdd	Supply voltage	Voltage input
8	GND	21	GND	Ground	
9	EOS	22	EOS	End of scan	Negative-going pulse output
10	Video	23	Video	Video output	Negative-going output from Vref
11	Vref	24	Vref	Reference voltage	Voltage input
12	Vgain	25	Vgain	Gain selection voltage	Voltage input
13	Vpd	26	Vpd	Photodiode voltage	Voltage input

# **→** Gain selection terminal voltage setting

Vdd: High gain (Cf=0.125 pF) GND: Low gain (Cf=0.25 pF)



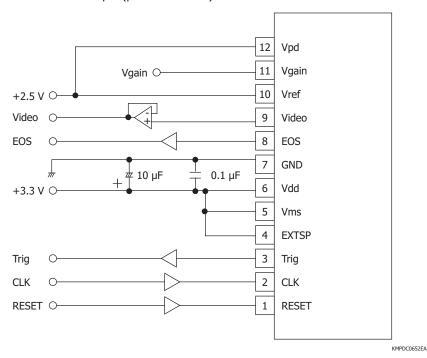
# Setting for each readout method

### S13885-128G, S13886-128G

Set to A in the table below in most cases.

To serially read out signals from two or more sensors linearly connected, set the 1st sensor to A and the 2nd or later sensors to B. The CLK and RESET pulses should be shared with each sensor and the video output terminal of each sensor connected together.

# ■ Connection example (parallel readout)



Note: When making a serial connection with two or more sensors or when connecting the sensor with a long cable, connect a high-impedance amplifier near the sensor if necessary.

Setting	Readout method	Vms	EXTSP
Α	All stages of parallel readout, serial readout at 1st sensor	Vdd	Vdd
В	Serial readout at 2nd and later sensors	GND	Preceding sensor EOS is input.

#### S13885-256G

Signals of channels 1 through 128 are output from CMOS1, while signals of channels 129 through 256 are output from CMOS2. The following two readout methods are available.

#### (1) Serial readout method

CMOS1 and CMOS2 are connected in serial and the signals of channels 1 through 256 are sequentially read out from one output line. Set CMOS1 as in "A" in the table below, and set CMOS2 as in "B". Use a common CLK for CMOS1 and CMOS2. Likewise, use a common RESET for CMOS1 and CMOS2. Connect the video output terminals to a single line.

### (2) Parallel readout method

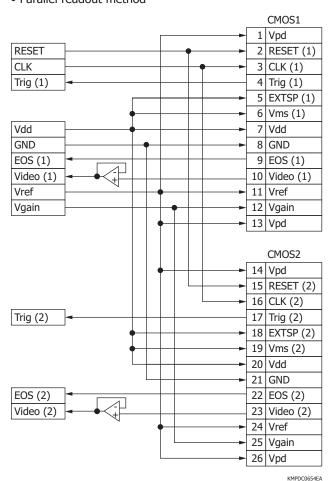
128 channel signals are output in parallel respectively from the output lines of CMOS1 and CMOS2. Set both CMOS1 and CMOS2 as in "A" in the table below.

#### ■ Connection examples

#### Serial readout method

#### CMOS1 Vpd RESET 2 RESET (1) CLK 3 CLK (1) 4 Trig (1) 5 EXTSP (1) 6 Vms (1) Vdd 7 Vdd **GND** 8 **GND** 9 EOS (1) 10 Video (1) Vref 11 Vref Vgain 12 Vgain 13 Vpd CMOS2 14 Vpd 15 RESET (2) Trig 16 CLK (2) OR Logic IC 17 Trig (2) 74HC32 18 EXTSP (2) 19 Vms (2) 20 Vdd 21 GND **EOS** 22 EOS (2) Video 23 Video (2) 24 Vref 25 Vgain 26 Vpd

#### • Parallel readout method



Note: When making a serial connection with two or more sensors or when connecting the sensor with a long cable, connect a high-impedance amplifier near the sensor if necessary.

Setting	Vms	EXTSP
Α	Vdd	Vdd
В	GND	Preceding sensor EOS is input.

# Photodiode arrays with amplifiers

S13885/S13886 series

#### Readout circuit

Apply pulse signals that meet the required conditions to the input terminals. Video output should be amplified by an op amp that is connected close to the sensor.

#### Precautions

- (1) The signal processing IC chip is protected against static electricity. However, in order to prevent possible damage to the IC chip, take electrostatic countermeasures such as grounding yourself, as well as workbench and tools. Also protect the IC chip from surge voltages from peripheral equipment.
- (2) Gold wires for wire bonding are very thin, so they easily break if subjected to mechanical stress. The signal processing IC chip and wire bonding are covered with resin for protection, but make sure they do not get scratched. Never touch these portions or the photodiode array chip affixed with the phosphor sheet. Excessive force, if applied, may break the wires or cause malfunction. Blow air to remove dust or debris if it gets on the protective resin. Never wash them with solvent. Signals may not be obtained if dust or debris is left or a scratch is made on the protective resin or the phosphor sheet or if the signal processing IC chip or photodiode array chip is nicked.
- (3) The photodiode array characteristics may deteriorate when operated at high humidity, so put it in a hermetically sealed enclosure or case. When installing the photodiode array with amplifier on a board, be careful not to cause the board to warp.
- (4) The characteristics of the signal processing IC chip deteriorate if exposed to X-rays. So use a lead shield which is at least 1 mm larger all around than the signal processing IC chip. The 1 mm margin may not be sufficient depending on the incident angle of X-rays. Provide an even larger shield as long as it does not cover the photodiode photosensitive area. Since the optimal shield thickness depends on the operating conditions, calculate it by taking the attenuation coefficient of lead into account.
- (5) The sensitivity of the photodiode array chip decreases if continuously exposed to X-rays. The extent of this sensitivity decrease differs depending on the X-ray irradiation conditions.

#### Related information

www.hamamatsu.com/sp/ssd/doc\_en.html

- Precautions
- Disclaimer
- · Image sensors

Information described in this material is current as of July 2017.

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